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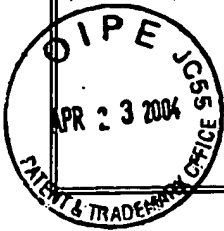
APPLICANT: LI et al.

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## U.S. PATENT DOCUMENTS

| EXAM.<br>INITIAL | DOCUMENT NUMBER | DATE         | NAME         | CLASS | SUBCLASS | FILING DATE IF<br>APPROPRIATE |
|------------------|-----------------|--------------|--------------|-------|----------|-------------------------------|
| my               | 5 7 5 3 5 2 3   | May 19, 1998 | Giedd et al. | —     | —        |                               |
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## FOREIGN PATENT DOCUMENTS

| DOCUMENT NUMBER | DATE | COUNTRY | CLASS | SUBCLASS | TRANSLATION |
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## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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| Robbins, H., and B. Schwartz, "Chemical Etching of Silicon: I. The System HF, HNO <sub>3</sub> , and H <sub>2</sub> O," <i>Journal of the Electrochemical Society</i> , vol. 106, no. 6, June 1959, pp. 505-508.   |
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| Yoon, Tae Hwan, Eun Jung Hwang, Dong Yong Shin, Se Ik Park, Seung Jae Oh, Sung Cheri Jung, Hyung Cheul Shin, and Sung June Kim, "A Micromachined Silicon Depth Probe for Multichannel Neural Recording," <i>IEEE Transactions on Biomedical Engineering</i> , vol. 47, no. 8, Aug. 2000.         |

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*my* 2/17/06